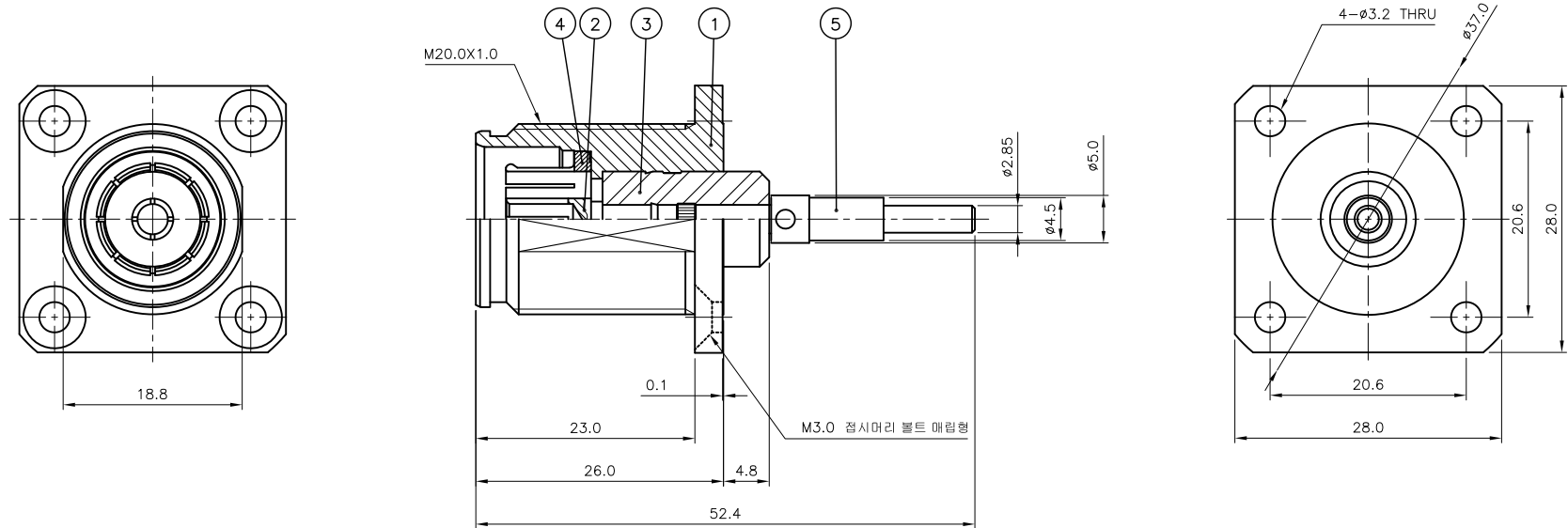


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1	Initial Registration	T.J.KIM	J.H.YOUN	2016.07.19.
2	업체요청 H-Cutting 추가	S.L.SON	J.H.YOUN	2017.02.07.
3	PIN 형상 변경	S.L.SON	J.H.YOUN	2019.08.07.
4	조립공차 ±0.1 -> ±0.2 변경	S.Y.EUN	I.C.KIM	2020.05.12.



5	CONTACT	1	MBsBD C3604BD-F	Silver Plate (3μm)	DCT03730-5/3
4	JACK	1	MBsBD C3604BD-F	Silver Plate (3μm)	DJA00228-5/6
3	INSULATOR	1	TEFLON		DIN02794-N/5
2	CONTACT	1	BeCu C17300	Silver Plate (5μm)	DCT03729-5/1
1	BODY	1	MBsBD C3604BD-F	SUCO Plate (3μm)	DBD04187-5/4
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE	2020. 05. 12.	 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL	±1°	CHECKED BY		KJ COMTECH CO., LTD. 4.3-10 DC BLOCK JS-4H
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	2/1	A3
		UNIT	mm	
		DWG NO.	CN03634-7/3	REVISION 4 SHEET 1 of 1